



# THERMINIC

**25<sup>th</sup> INTERNATIONAL WORKSHOP**  
*on Thermal Investigations of ICs and Systems*

**25-27 SEPTEMBER 2019**

**Politecnico di Milano – Lecco Campus**  
**Lecco (Italy)**

25<sup>th</sup> edition

2019

# THERMINIC

- THERMINIC is the major European Workshop dedicated to thermal issues in electronic components and systems.
- The next conference will be organized at Politecnico di Milano – Lecco Campus, in Lecco, Lake Como, Italy.



25<sup>th</sup> edition

2019

# THERMINIC

- The 25<sup>th</sup> edition holds a symbolic and strategic value. It will be a special occasion for academics and industrialists to get an insight to the latest advancements in the field of micro and power electronics and to draw a retrospect to the last decades of research along with an outlook to future directions.
- Carefully selected contributions and special social events, will also provide an opportunity to share knowledge and experiences in the exclusive scenery of Lake Como.



25<sup>th</sup> edition

2019

# THERMINIC

Delegates are invited to consider submitting abstracts related (but not limited) to:

- Thermal Phenomena, Simulation and Experiment
- Electronics Cooling Concepts
- Thermo-Mechanical Reliability

Special Sessions will be also organized.



## CONFERENCE TOPICS

25<sup>th</sup> edition

2019

# THERMINIC

*PROGRAM CHAIR &  
LOCAL ORGANIZER*

**Prof. Lorenzo Codecasa**  
Politecnico di Milano, DEIB

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*LOGISTIC*

**Politecnico di Milano**  
Lecco Campus

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**POLITECNICO**  
MILANO 1863

*FINANCE OPERATIONS*

**Fondazione Politecnico  
di Milano**



# ORGANIZERS



25<sup>th</sup> edition

2019

# THERMINIC

ADDRESS:

**Politecnico di Milano – Lecco Campus**

Via Gaetano Prevati, 1/C

23900, Lecco, IT

CONFERENCE SPACES WILL FEATURE:

- **1 Conference Room**  
(180 seats)
- **Main hallway**  
(for poster exhibition, and exhibition stands for sponsors)
- **1 Meeting point**  
(to facilitate talks, and work meetings)

## VENUE



25<sup>th</sup> edition

2019

# THERMINIC

Over the years THERMINIC has proved to be an ideal platform to provide companies with international exposure for their products, as well as services to enhance their standing and reputation in the industry field related to thermal issues and electronic components.

The conference organizers have tailored different sponsorship options. Each one guarantees recognition in the official Program Guide, prominent signage when possible, and acknowledgment from the stage by THERMINIC 2019 as often as possible.



CONTACT INFO:  
**Mrs. Maria R. Francolino**  
[maria.francolino@fondazione.polimi.it](mailto:maria.francolino@fondazione.polimi.it)

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2019

# THERMINIC

THERMINIC has been possible thanks to the continuing support provided by our sponsors.

If your company is willing to enlist as sponsor for THERMINIC 2019, you may consider the following proposals:

## FULL FLEDGED SPONSORSHIP

**Gold** : Conference Advertising + Conference Stand + vendor talk presentation (on demand) + full conference package for two participants 3000 Eur + VAT.

**Silver** : Conference Advertising + exhibition table, full conference package for one participant 2000 Eur + VAT.

## SPECIAL DEAL:

Support limited to a particular **social event**; providing **conference prizes**, or else, **tailor made arrangements** can be defined with our referees at Fondazione Politecnico di Milano.



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FULL FLEDGED SPONSORSHIP: **GOLD** 3000 Eur + VAT

## Sponsorship benefits include:

- Recognition of sponsorship on all conference related material (conference proceedings, Conference Program Guide, call for papers).
- Listing and Logo in the Sponsor tab of the conference webpage with links and contact info (if requested).
- full conference package for **2** participants.
- Acknowledgment of your sponsorship at events.
- Vendor talk/presentation (on demand).
- Exhibition table. Exhibitors will receive, an exhibition space of 6 m<sup>2</sup> minimum. An exhibition stand along with 2 chairs, their logo and short company profile on the conference website.



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FULL FLEDGED SPONSORSHIP: **SILVER** 2000 Eur + VAT

## Sponsorship benefits include:

- Recognition of sponsorship on all conference related material (conference proceedings, Conference Program Guide).
- Listing and Logo in the Sponsor tab of the conference webpage.
- Full conference package for **1** participant.
- Acknowledgment of your sponsorship at events.
- Exhibition table. Exhibitors will receive, an exhibition space of 6 m<sup>2</sup> minimum. An exhibition stand along with 2 chairs, their logo and short company profile on the conference website.



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## SPECIAL DEAL

Support to the conference is not limited to the ordinary full-fledged sponsorship. In case you are new to THERMINIC and yet willing to engage you may consider the following options:

- **Exhibitor** (1000 + VAT)
- **Cocktail Sponsor** (1000 Eur + VAT)
- **Break Sponsor** (500 Eur + VAT)

Exhibitors will receive: 1 exhibition space of 6m<sup>2</sup> minimum; 1 exhibition table 120 x 80 cm with 2 chairs; their logo and short company profile on the website. Cocktail Sponsors and Break Sponsors will receive: recognition in announcement, slide on beamer, signage and mention in the conference proceedings.

Further options could be also explored and defined with our referees at Fondazione Politecnico di Milano.



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**25-27 SEPTEMBER 2019 | Politecnico di Milano – Lecco Campus, Lecco (Italy)**

**Organized by POLITECNICO DI MILANO (ITALY)**

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